

WHAT IS CLAIMED IS:

1. A semiconductor device mounted on a mother board, comprising:

5 a circuit board to be positioned on said mother board; and

a semiconductor chip positioned on said circuit board; wherein

10 (a) said circuit board has a connection pad, a relay pad spaced away from said connection pad, and a wire connecting between said connection pad and said relay pad on a surface of said circuit board supporting said semiconductor chip;

15 (b) said semiconductor chip has a connection pad corresponding to said connection pad formed on said circuit board; and

(c) said connection pad on said circuit board and said connection pad on said semiconductor chip are electrically connected through a bonding wire.

20 2. A semiconductor device in accordance with claim 1, wherein said wire connecting between said connection pad and said relay pad on said circuit board is printed on said circuit board with said connection pad and said relay pad.

25 3. A semiconductor device in accordance with claim 1,

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wherein said wire connecting between said connection pad and said relay pad on said circuit board is a bonding wire.

4. A semiconductor device, comprising:

5 a first semiconductor chip having a connection pad;

a second semiconductor chip positioned on said first semiconductor chip, said second semiconductor chip having a connection pad, wherein said electrode on said second semiconductor chip is electrically connected with said connection pad on said first semiconductor chip.

5. A semiconductor device in accordance with claim 5,
wherein said connection pad on said first semiconductor
chip is connected with said connection pad on said second
semiconductor chip through a bonding wire.

6. A semiconductor device in accordance with claim 5,
wherein said connection pad on said first semiconductor
chip positions in a region where said first semiconductor
faces to said second semiconductor chip, said connection
pad on said second semiconductor chip in said region, and
said connection pad on said first semiconductor chip is
electrically connected with said connection pad on said
second semiconductor chip through a conductive member

~~positioned in said region.~~

7. A wiring method, comprising the steps of:

providing a first semiconductor chip having a
5 connection pad;

positioning a second semiconductor chip on said
first semiconductor chip, said second semiconductor chip
having a connection pad; and

10 electrically connecting between said connection
pad of said first semiconductor chip and said connection
pad of said second semiconductor chip.

8. A wiring method in accordance with claim 7,

wherein said connection pad of said first semiconductor
15 chip is electrically connected with said connection pad of
said second electrode through a bonding wire.

9. A wiring method in accordance with claim 8,

wherein said connection pad on said first semiconductor
20 chip positions in a region where said first semiconductor
faces to said second semiconductor chip, said connection
pad on said second semiconductor chip positions in said
region, and said connection pad on said first semiconductor
chip is electrically connected with said connection pad on
25 said second semiconductor chip through a conductive member

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positioned in said region.

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